

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Vyvoda et al.	
Application No.: 10/681,507	Group Art Unit: 2813
Filed: 10/07/2003	
Title: Electrically Isolated Pillars in Active Devices	Examiner: Laura M. Schillinger
Attorney Docket No.: 3558P027D	

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

August 18, 2005

DECLARATION UNDER 37 CFR §1.132

To the Commissioner:

As an inventor of Lee et al., US Patent No. 6,881,994 and one skilled in the art of submicron semiconductor fabrication, I, James M. Cleeves, hereby declare my opinion that:

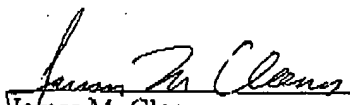
1. Formation of the structure pictured in Figs. 9a and 9b of Lee et al., US Patent No. 6,881,994, involves two patterning steps. The first patterning step forms strip 904. The second patterning step forms conductor 906 and pillar 908. Though not shown, dielectric fill is supporting the apparently unsupported section of conductor 906. This dielectric fill was deposited in a dielectric fill step performed between the first and second patterning steps. Other steps are also performed after the deposition of dielectric fill and before the second patterning step, including polish of dielectric fill to expose the top of strips 904

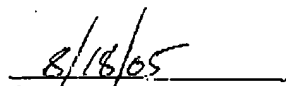
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and deposition of layer 906. The first and second patterning steps forming the structure of Figs. 9a and 9b of Lee et al. thus are not performed back-to-back, i.e. with no intervening dielectric fill step.

2. From Figs. 9a and 9b of Lee et al. and the accompanying description, one skilled in the art of submicron semiconductor fabrication would assume that a dielectric fill step, as well as a polishing step to expose the tops of strips 904 and a deposition step to deposit layer 906, was performed between the two patterning steps that form the structure of Figs. 9a and 9b, and thus that these patterning steps are not performed back-to-back with no intervening dielectric fill step, even though this dielectric fill step is not explicitly detailed in the description of Figs. 9a and 9b.
3. All statements made herein of my own knowledge are true, and all statements made on information and belief are believed to be true. Further, these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful statements may jeopardize the validity of the application or any patent issuing therefrom.

Respectfully submitted,


James M. Cleaves


Date

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